WHAT IS CLAIMED IS:

1. A drop ejector, comprising:

a flow path in which fluid is pressurized to eject drops from a nozzle opening formed in a substantially planar substrate, and a channel formed in the substrate proximate the nozzle opening, the channel being spaced from the nozzle opening by a distance of about 20 % of a nozzle width or more.

2. The drop ejector of claim 1 wherein the nozzle opening is surrounded by the channel.

3. The drop ejector of claim 2 wherein the channel is in the shape of a circle.

4. The drop ejector of claim 1 wherein the channel extends radially from the nozzle opening.

5. The drop ejector of claim 1 wherein the channel has a width that is about twice the nozzle opening width or less.

6. The drop ejector of claim 1 wherein the channel has a width of about 100 microns or less.

7. The drop ejector of claim 1 wherein a depth of the channel is from about 2 micron to about 50 micron.

8. The drop ejector of claim 1 wherein the substrate is a silicon material.

9. The drop ejector of claim 1 wherein the planar substrate includes a plurality of nozzle openings and channels proximate the nozzle openings.

10. The drop ejector of claim 1 wherein the nozzle opening width is about 200 micron or less.

11. The drop ejector of claim 1 including a piezoelectric actuator.

12. A method of fluid ejection, comprising:

providing a drop ejector including a flow path in which fluid is pressurized for ejection through a nozzle opening formed in a substrate, and a channel formed in the substrate proximate the nozzle opening, the channel being spaced from the nozzle opening by a distance of about 20 % of the nozzle width or more;

providing a fluid that is wicked by capillary forces into the space defined by said channel, and

ejecting said fluid through said nozzle opening by pressurizing said fluid in said flow path.

13. The method of claim 12 wherein the fluid has a surface tension of about 20-50 dynes/cm.

14. The method of claim 12 wherein the fluid has a viscosity of about 1 to 40 centipoise.